

MARKED-UP VERSION SHOWING CHANGES MADE**IN THE CLAIMS:**

Please **amend** claims 14 and 18, as follows:

14. **(Amended)** A method of manufacturing a semiconductor device
[according to claim 8,] comprising the steps of:

(a) providing a semiconductor chip having a plurality of semiconductor elements and a plurality of external terminals formed on a main surface thereof;

(b) providing a wiring substrate having a plurality of wirings and an opening, the wirings are revealed on a main surface of the wiring substrate and a layer having adhesion is applied on a rear surface of the wiring substrate, opposite of the main surface thereof,

wherein the step (b) comprises a step of forming the layer on the rear surface of the wiring substrate by printing;

(c) adhering the main surface of the semiconductor chip on the rear surface of the wiring substrate by way of the layer as the layer is protruding from an outer periphery of the semiconductor chip;

(d) electrically connecting the plurality of wirings with the plurality of external terminals through the opening, respectively, and

(e) after the step (d), cutting the wiring substrate together with the layer to form outer peripheries thereof outside of the outer periphery of the semiconductor chip.

18. **(Amended)** A method of manufacturing a semiconductor device

[according to claim 17] comprising the steps of:

(a) providing a semiconductor chip having a plurality of semiconductor elements and a plurality of external terminals formed on a main surface thereof;

(b) providing a wiring substrate, comprised of a polyimide tape, having a plurality of wirings and an opening, the wirings are revealed on a main surface of the wiring substrate and a layer having adhesion and a thickness larger than that of the wiring substrate is applied on a rear surface of the wiring substrate, opposite of the main surface thereof;

wherein the step (b) comprises a step of forming the layer on the rear surface of the wiring substrate by printing,

(c) adhering the main surface of the semiconductor chip on the rear surface of the wiring substrate by way of the layer as the layer is protruding from an outer periphery of the semiconductor chip;

(d) electrically connecting the plurality of wirings with the plurality of external terminals through the opening, respectively, and

(e) after the step (d), cutting the wiring substrate together with the layer to form outer peripheries thereof outside of the outer periphery of the semiconductor chip,

wherein the wiring substrate and the layer are cut along a same cutting line.